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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Confirmation No. 2272

Group Art Unit: 2814

Examiner: Dilinh P. Nguyen

Inventor(s): Jung-Yu Lee et al.

Serial No.: 09/746,018

Filing Date: December 26, 2000

Title: SEMICONDUCTOR PACKAGE FOR EFFICIENT HEAT SPREADING

Attorney Docket No. 46599-00254

AMENDMENT UNDER 37 C.F.R. §1.312

Mail Stop Issue Fee
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

OK to exec

Dilinh Nguyen
9/12/05

Dear Sir:

Applicants hereby acknowledge receipt of the Notice of Allowance and Fee(s)
Due mailed July 1, 2004.

Please amend the above-identified patent application as follows:

Amendments to the Specification begin on page 2 of this paper.

Amendments to the Abstract begin on page 12 of this paper.

Remarks begin on page 13 of this paper.